

ABSTRACT

Interconnection structures for integrated circuits have a first array of cells, at least a second array of cells parallel to the first array, and interconnections
5 disposed for connecting cells of the first array with cells of the second array, at least some of the interconnections being disposed along axes oriented obliquely to the first and second arrays. First and second sets of oblique axes of interconnections may be parallel or opposed to each other. The interconnections may include obliquely slanted pillars or stair-stepped pillars disposed along the
10 oblique axes. Methods for fabricating and using such structures are disclosed.